

Standard

- DAB
Digital audio broadcasting

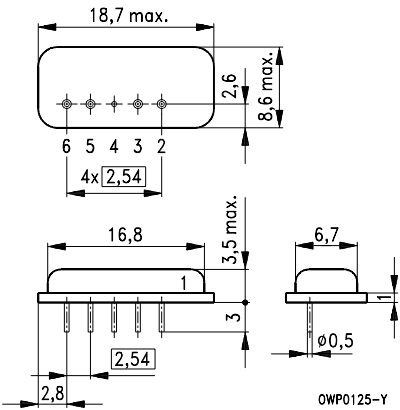
Features

- Bandpass filter for DAB applications
- Constant group delay
- Hermetically sealed metal package

Terminals

- Tinned NiFeCo alloy

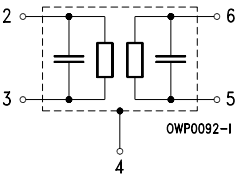
Metal package SIP 6 M



Dimensions in mm, approx. weight 3,0 g

Pin configuration

- 2 Input
- 3 Input – ground
- 5 Output
- 6 Output
- 4 Case – ground



Type	Ordering code	Marking
B 512	B39390-B512-X110	Type, date code, pin 1

Electrostatic Sensitive Device (ESD)

Maximum ratings

Ambient temperature	T_A	- 25/+ 85	°C	—
Storage temperature	T_{stg}	- 40/+ 85	°C	—
DC voltage	V_{DC}	0	V	—
Source power	P_s	15	dBm	source impedance 50 Ω

Characteristics

Ambient temperature
Source impedance
Load impedance
Group delay aperture

$T_A = 25\text{ }^{\circ}\text{C}$
 $Z_S = 50\text{ }\Omega$ and matching network
 $Z_L = 50\text{ }\Omega$ and matching network
80 kHz

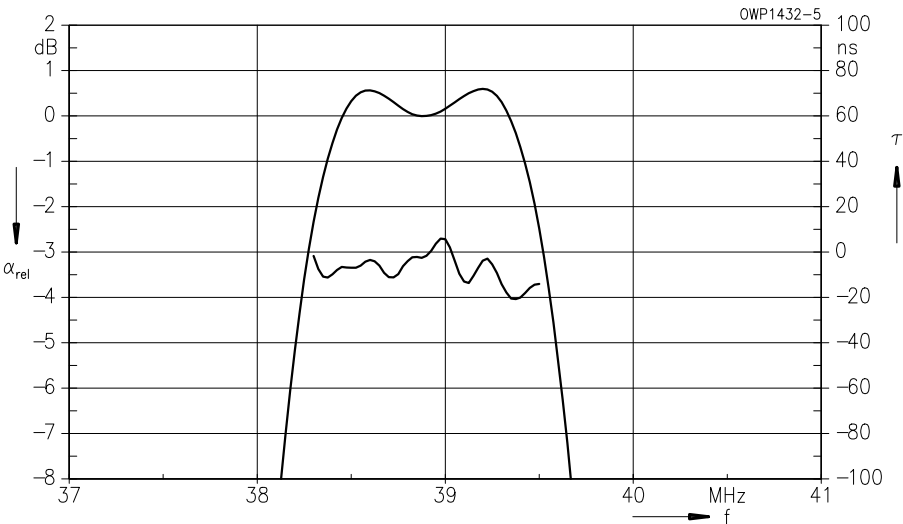
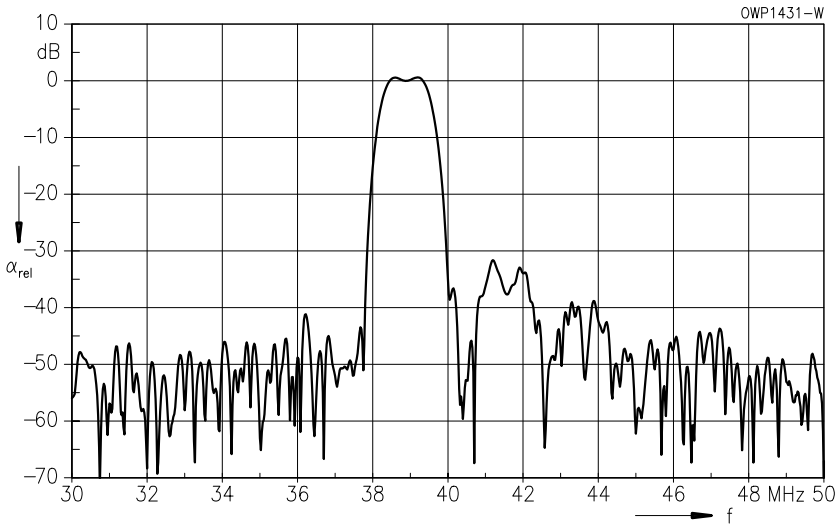
		min.	typ.	max.	
Nominal frequency	f_N	—	38,912	—	MHz
Insertion attenuation at f_N	α_N	—	22,00	—	dB
Pass bandwidth					
$\alpha_{\text{rel}} \leq 3\text{ dB}$	$B_{3\text{dB}}$	1,15	1,25	1,35	MHz
$\alpha_{\text{rel}} \leq 10\text{ dB}$	$B_{10\text{dB}}$	—	1,60	1,75	MHz
$\alpha_{\text{rel}} \leq 20\text{ dB}$	$B_{20\text{dB}}$	—	1,90	2,05	MHz
$\alpha_{\text{rel}} \leq 30\text{ dB}$	$B_{30\text{dB}}$	—	2,10	—	MHz
Relative attenuation (relative to α_N)					
Lower sidelobe	30,00 ... 37,40 MHz	38,00	41,00	—	dB
Upper sidelobe	40,40 ... 42,40 MHz	28,00	31,00	—	dB
	42,40 ... 50,00 MHz	34,00	37,00	—	dB
Reflected wave signal suppression					
2,0 μs ... 6,0 μs after main pulse		40,0	45,0	—	dB
Group delay at f_N	τ_N	—	1,75	—	μs
Group delay ripple (p-p)	38,30 ... 39,50 MHz $\Delta\tau$	—	25	—	ns
Temperature coefficient of frequency	TC_f	—	- 0,035	—	ppm/K ²

Matching network:

Input: Serial coil; L 1 = 3,3 μH , Q = 30

Output: Serial coil; L 2 = 6,8 μH , Q = 30

Frequency response



Standard

- DAB

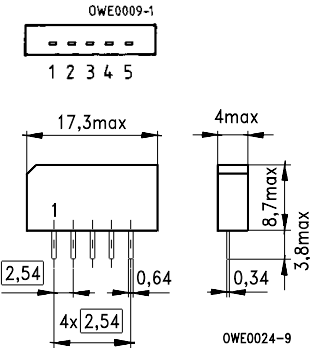
Features

- IF filter for Digital Audio Broadcasting
- Low group delay ripple

Terminals

- Tinned CuFe alloy

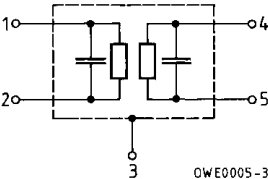
Plastic package SIP 5 K



Dimensions in mm, approx. weight 1,0 g

Pin configuration

- 1 Input
- 2 Input – ground
- 3 Chip carrier – ground
- 4 Output
- 5 Output



Type	Ordering code	Marking
X 6922 M	B39389-X6922-M100	Type, date code, pin 1

Maximum ratings

Ambient temperature	T_A	- 25/+ 65	°C	—
Storage temperature	T_{stg}	- 25/+ 85	°C	—
DC voltage	V_{DC}	12	V	between any terminals
AC voltage	V_{pp}	10	V	between any terminals

X 6922 M

38,912 MHz

Characteristics

Ambient temperature	$T_A = 25\ (40)^\circ\text{C}$
Source impedance	$Z_S = 50\ \Omega$
Load impedance	$Z_L = 2\ \text{k}\Omega \parallel 3\ \text{pF}$
Group delay aperture	50 kHz

		min.	typ.	max.	
Center frequency (center between 10 dB points)	f_c	—	(38,912)	—	MHz
Insertion attenuation Reference level for the following data	α 38,922 (38,912) MHz	17,2	18,7	20,2	dB
Pass bandwidth $\alpha_{\text{rel}} \leq 3\ \text{dB}$	$B_{3\text{dB}}$	—	1,5	—	MHz
$\alpha_{\text{rel}} \leq 30\ \text{dB}$	$B_{30\text{dB}}$	—	2,65	—	MHz
Relative attenuation Lower sidelobe	α_{rel}				
30,01 ... 36,02 (30,00 ... 36,01) MHz		43,0	48,0	—	dB
36,02 ... 37,22 (36,01 ... 37,21) MHz		38,0	44,0	—	dB
Upper sidelobe					
40,62 ... 41,82 (40,61 ... 41,81) MHz		38,0	43,0	—	dB
41,82 ... 50,01 (41,81 ... 50,00) MHz		41,0	45,0	—	dB
Reflected wave signal suppression 1,6 μs ... 6,0 μs after main pulse (test pulse: 250 ns, carrier frequency: 38,922 MHz)		42,0	55,0	—	dB
Feedthrough signal suppression 1,5 μs ... 1,4 μs before main pulse (test pulse: 250 ns, carrier frequency: 38,922 MHz))		50,0	56,0	—	dB
Group delay ripple (p-p) 38,12 ... 39,72 (38,11 ... 39,71) MHz	$\Delta\tau$	—	35	—	ns
Impedance at 38,922 MHz Input: $Z_{\text{IN}} = R_{\text{IN}} \parallel C_{\text{IN}}$ Output: $Z_{\text{OUT}} = R_{\text{OUT}} \parallel C_{\text{OUT}}$		—	1,0 $\parallel$ 25,3 0,9 $\parallel$ 15,0	—	—
Temperature coefficient of frequency	TC_f	—	- 18	—	ppm/K

Frequency response

